DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

(Application Serial No.)

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor

entitled:	e listed below) of the subject		d and for which a patent is sound to the same	ught on the invention
	f which is attached hereto un ctober 8, 2004 as	-	ecked ion Number or PCT Internatio	onal
Application Nu	mber PCT/JP2004/015	and was amended	on (if applicable).	
	I have reviewed and understa led by any amendment referr		above-identified specification,	including the
I acknowledge the Regulations, § 1.56		which is material to pa	tentability as defined in Title	37, Code of Federal
for patent or inven	tor's certificate listed below	and have also identified	ode, § 119 (a) – (d) of any for I below any foreign application	n for patent or
	ite naving a thing date before	e that of the application	for which priority is claimed.	Priority Claimed
(List prior foreign applications. See note A)	2003-350406 (Number)	Japan (Country)	09/10/2003 (Day/Month/Year Filed)	X Yes No
	(Number)	(Country)	(Day/Month/Year Filed)	Yes No
			·	☐ Yes ☐ No
	(Number)	(Country)	(Day/Month/Year Filed)	
	(Number)	(Country)	(Day/Month/Year Filed)	☐ Yes ☐ No
(See note B)	See attached list for	additional prior foreign	applications	
insofar as the subjoin the manner proving information which	ect matter of each of the claim wided by the first paragraph is material to patentability	ms of this application is of Title 35, United Stat as defined in Title 37,	f any United States application in the prior United States application of the prior United Code, § 112, I acknowled a Code of Federal Regulations, national or PCT internation	ited States application ge the duty to disclose § 1.56 which became al filing date of this
(List prior U.S.			Stat	tus
Applications)	Application Serial No.)	(Filing Date)	Patented Pend	ding Abandoned
	Application Serial No.)	(Filing Date)	Patented Pend	ding Abandoned
			Patented Pend	ding

(Filing Date)

I hereby appoint the followin orney(s) and/or agent(s) to prosecute this app. ion and to transact all business in the Patent and Trademark Office connected therewith:

Please direct all of

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PATENT TRADEMARK OFFICE

direct all communications to the following address:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)	Full name of sole or f	irst inventor (given name, family name) WADA Isao
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·	Inventor's signature	•	Date
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